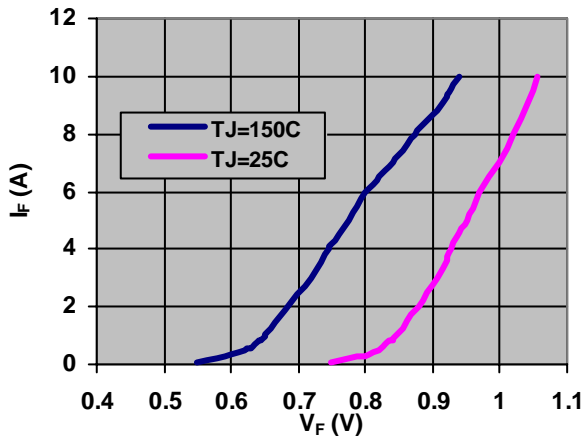
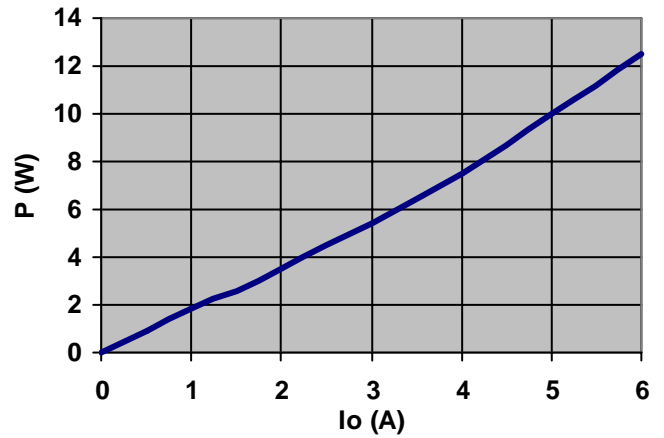


T10XB Series (SIP)

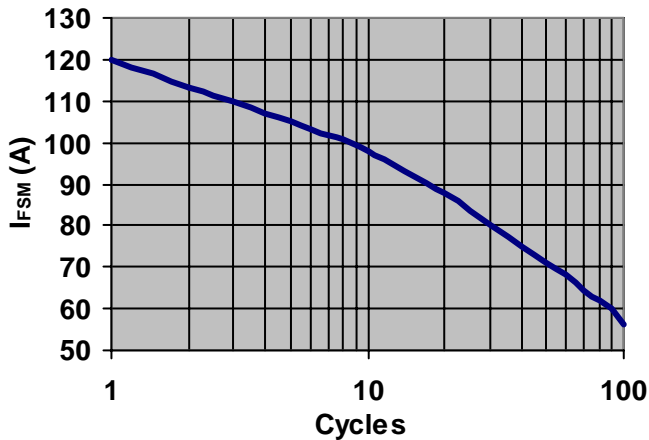
Forward Voltage



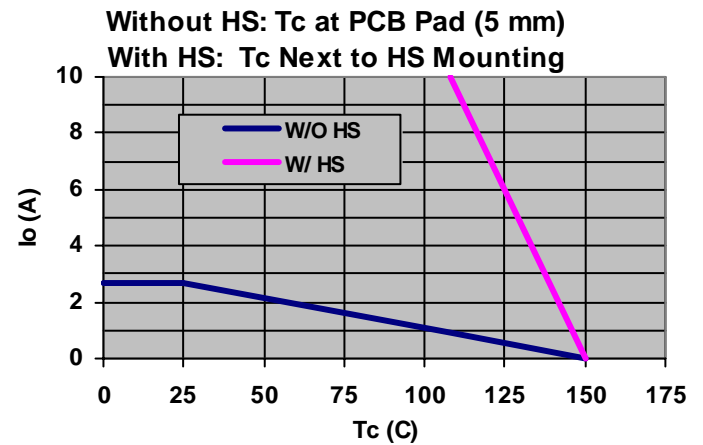
P - I_o Curve



Surge Forward Current



Current Derating



In order to avoid damaging devices, please observe the following precautions:

1. When using automated soldering equipment, use 60/40 (Sn/Pb) solder (melting point of 180°C) with a neutral flux similar to rosin. Preheat time should be limited to 1 – 2 minutes at 150°C .
2. When using a soldering iron, use a tip temperature of less than 300°C (or a soldering iron power of less than 60W). Keep the soldering time below 5 seconds.
3. After soldering, remove any flux residue to avoid corrosion.
4. Because over-voltage or over-current testing may cause permanent damage to the devices, be sure to check the test equipment for proper voltage, current and ground connection prior to beginning the test.
5. If the devices are to be encapsulated, they should be cleaned and dried at $120^\circ \pm 5^\circ\text{C}$ for at least 24 hours prior to encapsulation. Test for compatibility between the device package and the encapsulation material.